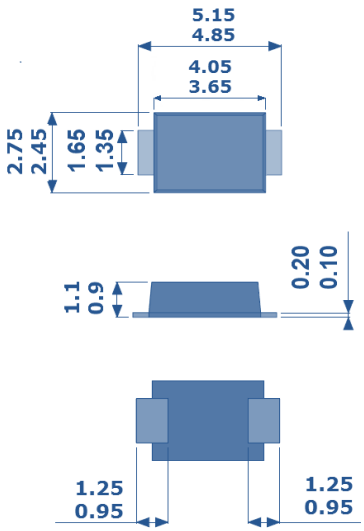
1. 封裝 Package

- 封裝方式 Method: SMAF
- 封裝尺寸 Dimension: 如圖示



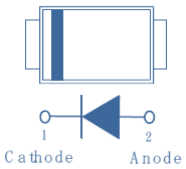
單位 Unit: millimeters

2. 產品特色 Features

- For surface mounted applications in order to optimize board space
- High surge capacity
- Low power loss, high efficiency.
- Package suitable for Automated Handling
- Ultra Thin Profile Package for Space Constrained Utilization
- Meet with EU RoHS 2011/65/EU compliance
- Lead free and Green device

3. 機械數據 Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Epoxy, Molded
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end



4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbol	SS22AF	SS24AF	SS26AF	UNITS
Marking Code	-	SS22A	SS24A	SS26A	-
Recurrent Peak Reverse Voltage	V_{RRM}	20	40	60	Volts
RMS Voltage	V_{RMS}	14	28	42	Volts
DC Blocking Voltage	V_R	20	40	60	Volts
Average Forward Current	$I_{F(AV)}$	2.0			Amps
Peak Forward Surge Current 8.3ms single half sine -wave superimposed on rated load (JEDEC Method)	I_{FSM}	50			Amps
Forward Voltage at 2.0A	V_F	0.5		0.7	Volts
DC Reverse Current at Rated DC Blocking Voltage T_J=25°C	I_R	0.1			mA
Typical Thermal Resistance, Junction to Lead (NOTE1) Junction to Ambient (NOTE1)	$R_{\theta JL}$ $R_{\theta JA}$	20 83			°C/W
Operating Junction Temperature and Storage Temperature Range	T_J, T_{STG}	-55~+150			°C

Notes:

(1) Mounted on 48cm^2 FR-4 PCB.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

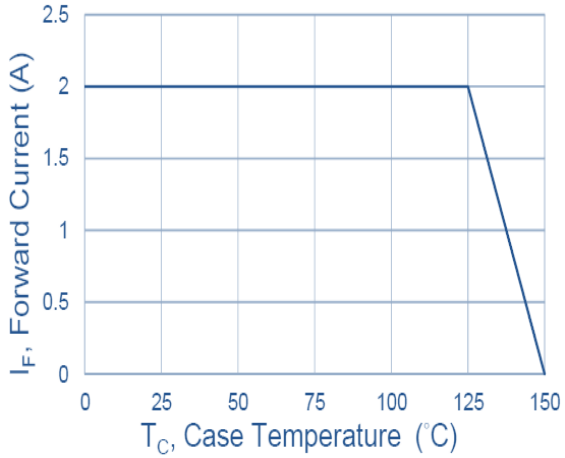


Fig. 2 Typical Reverse Characteristics

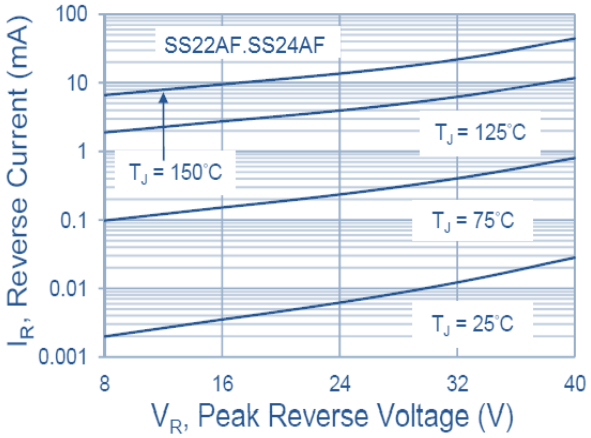


Fig. 3 Typical Reverse Characteristics

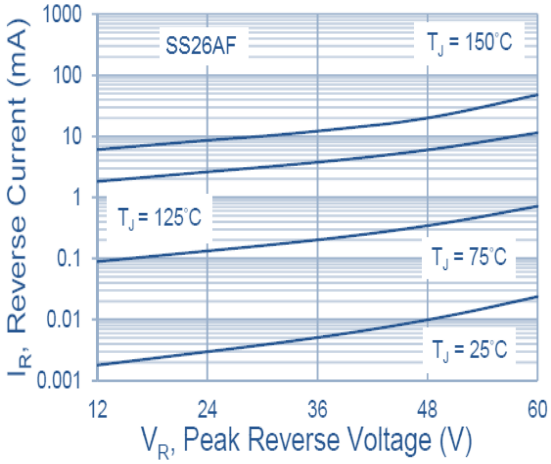


Fig. 4 Typical Forward Characteristics

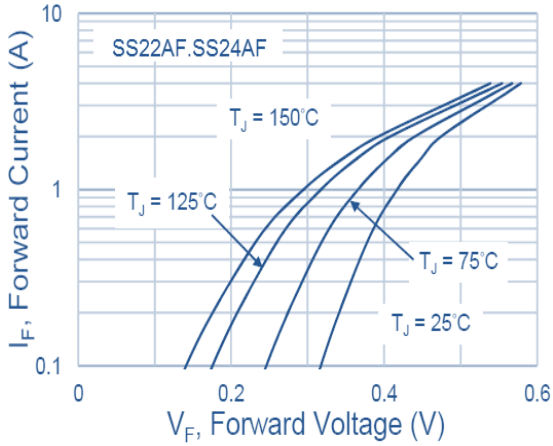
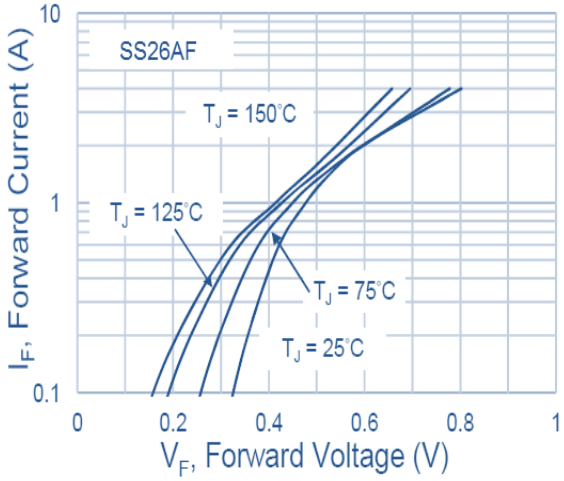
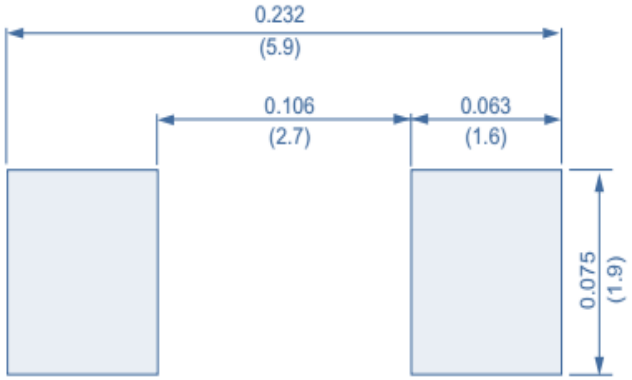


Fig. 5 Typical Forward Characteristics



Pad Layout



Unit: inch (mm)